

Backplanes 6 U



Front view, 6 U

Number of layers	8, 10 (for 6 U)
Layer structure	2 GND Layer
PCB thickness	3.2 mm
Data transfer rate	132/264 MBytes/32, 64-bit
Power inlets	6 U: Via screws and busbars
Control connector	+3.3 V, +5 V, +12 V, -12 V
VI/O (6 U)	Adjustable to +5 V or +3.3 V
CPU-slot	on right (left upon request)
Standards	PCI 2.1 (PCI Spec) PICMG 2.0 (CompactPCI) PICMG 2.1 (hot swap) IEEE 1101.1/10/11
Installation height	6 U
Distance between slots	4 HP
Connectors	J1, J2 32 or 64 bit J3, J4, J5 for rear I/O (64 bit only)
Operating temperature range	0° – 70°C
Relative humidity	90 %, non-condensing
Geographic addressing	64-bit versions

Backplanes 6 U for low profile bridge

Slot	Design	Order No.	
		32-bit	64-bit
2	S	3689.314	3689.321
3	SE	3689.315	3689.322
4	SBME	3689.316	3689.323
5	SBME	3689.317	3689.324
6	SBME	3689.318	3689.325
7	SBE	3689.319	3689.326
8	S	3689.320	3689.327

S = Stand alone
B = Beginning segment

M = Middle segment
E = Ending segment

Material:

Fibreglass epoxy to IEC 60 249 (type FR4)

Supply includes:

Backplane, fully populated.